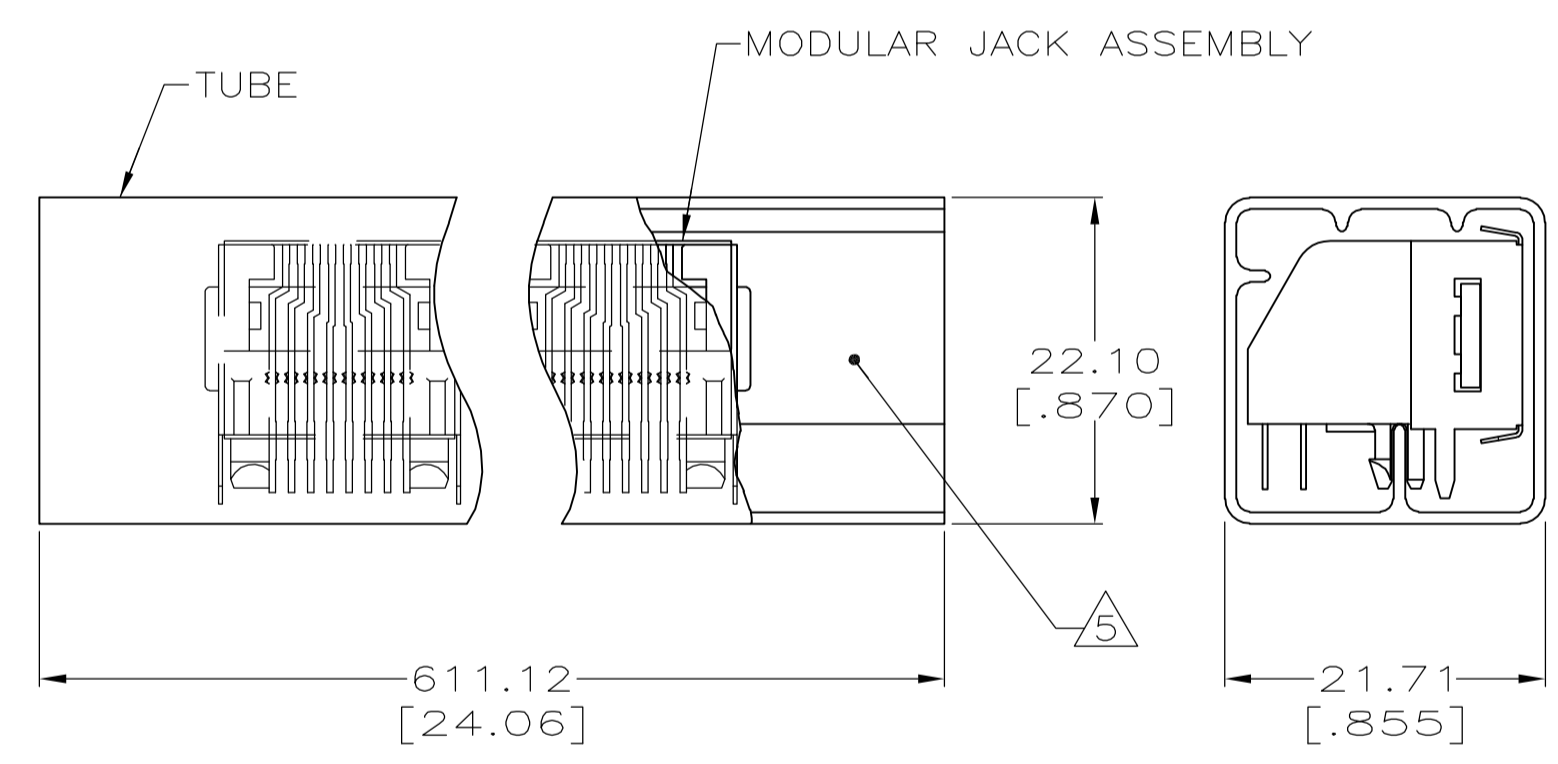
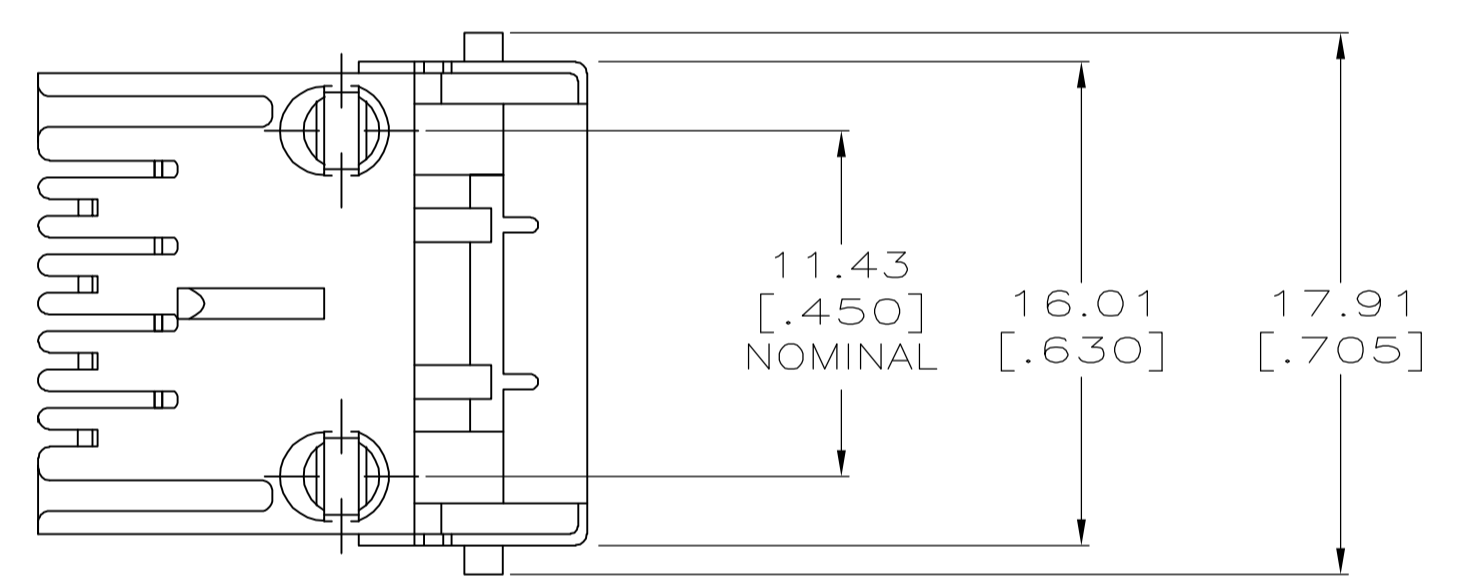
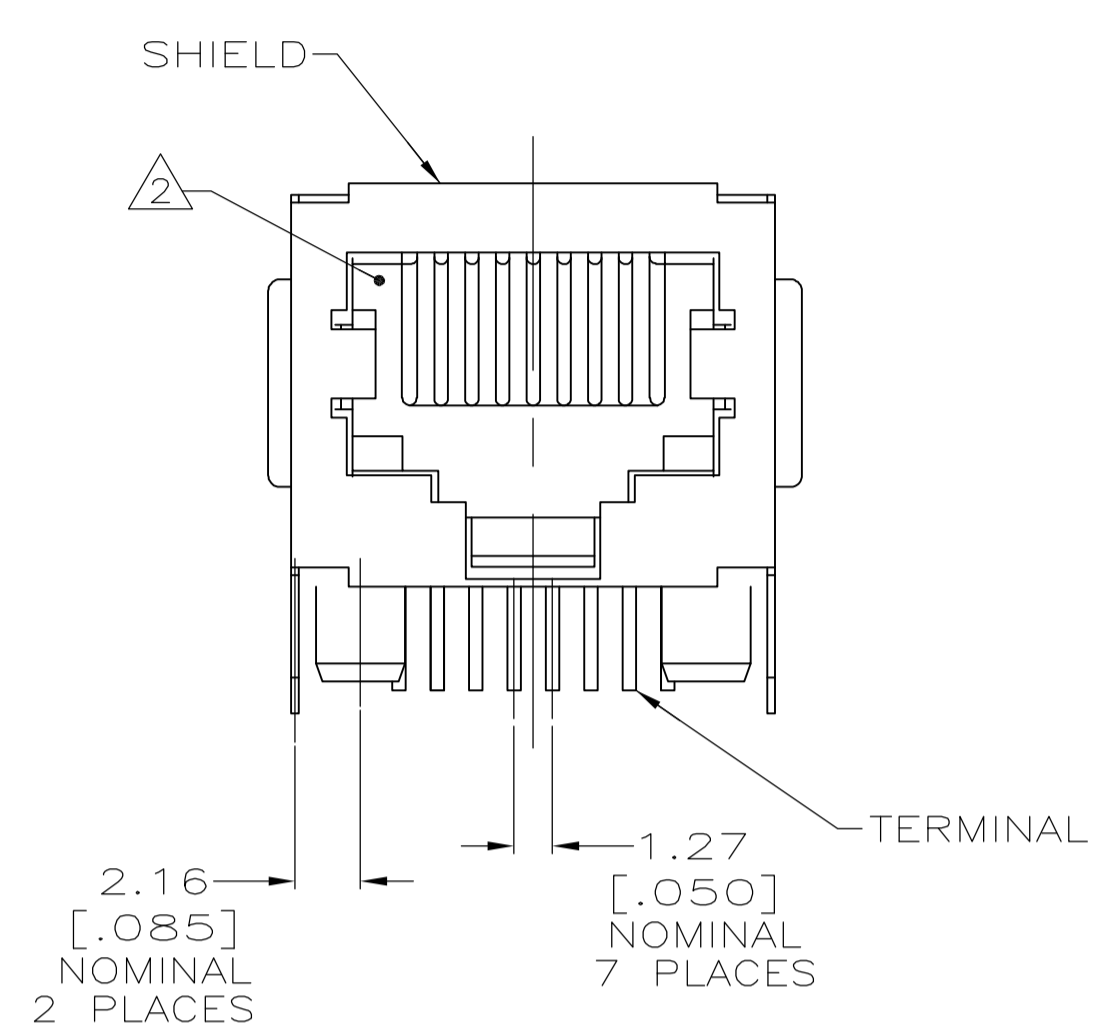
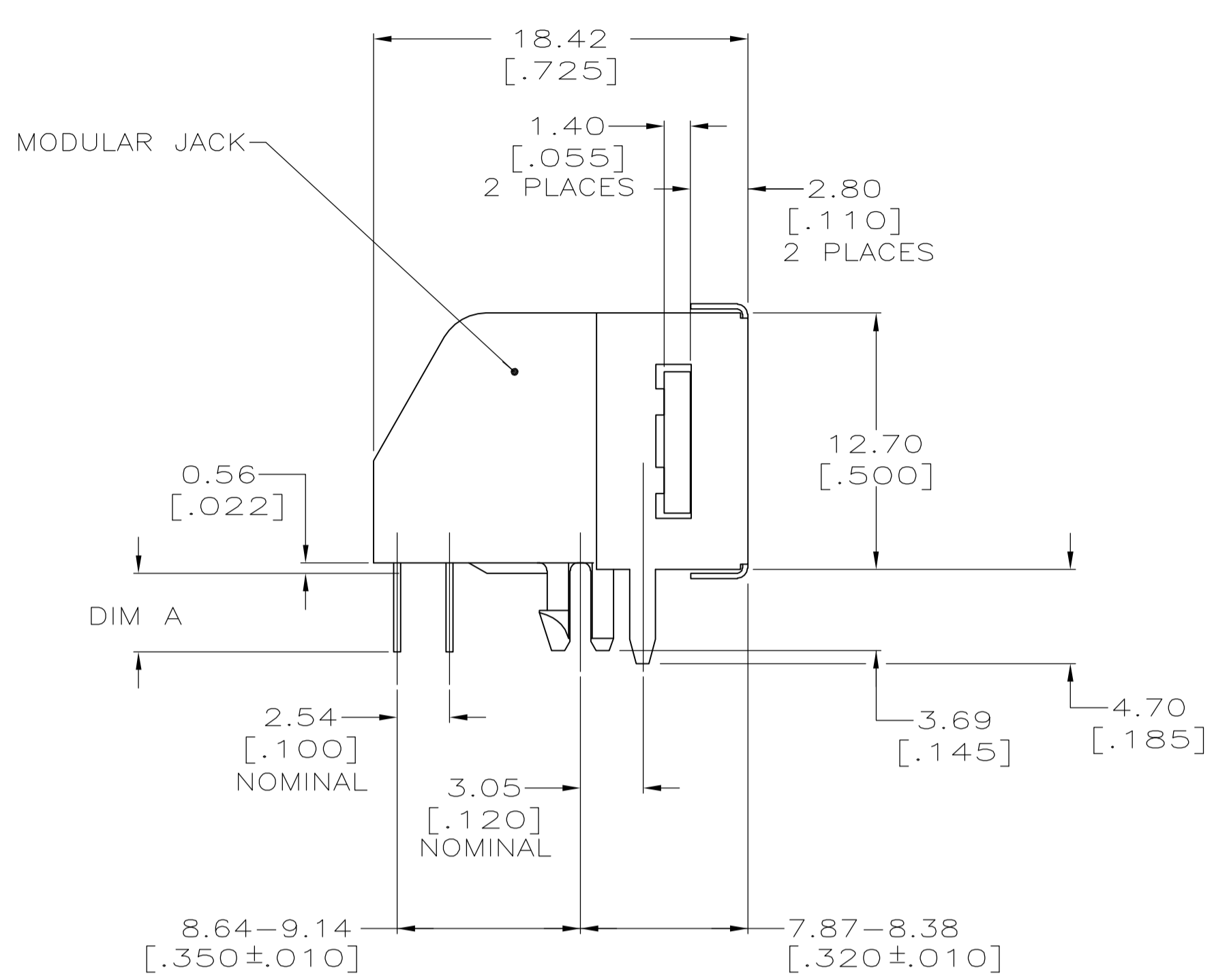
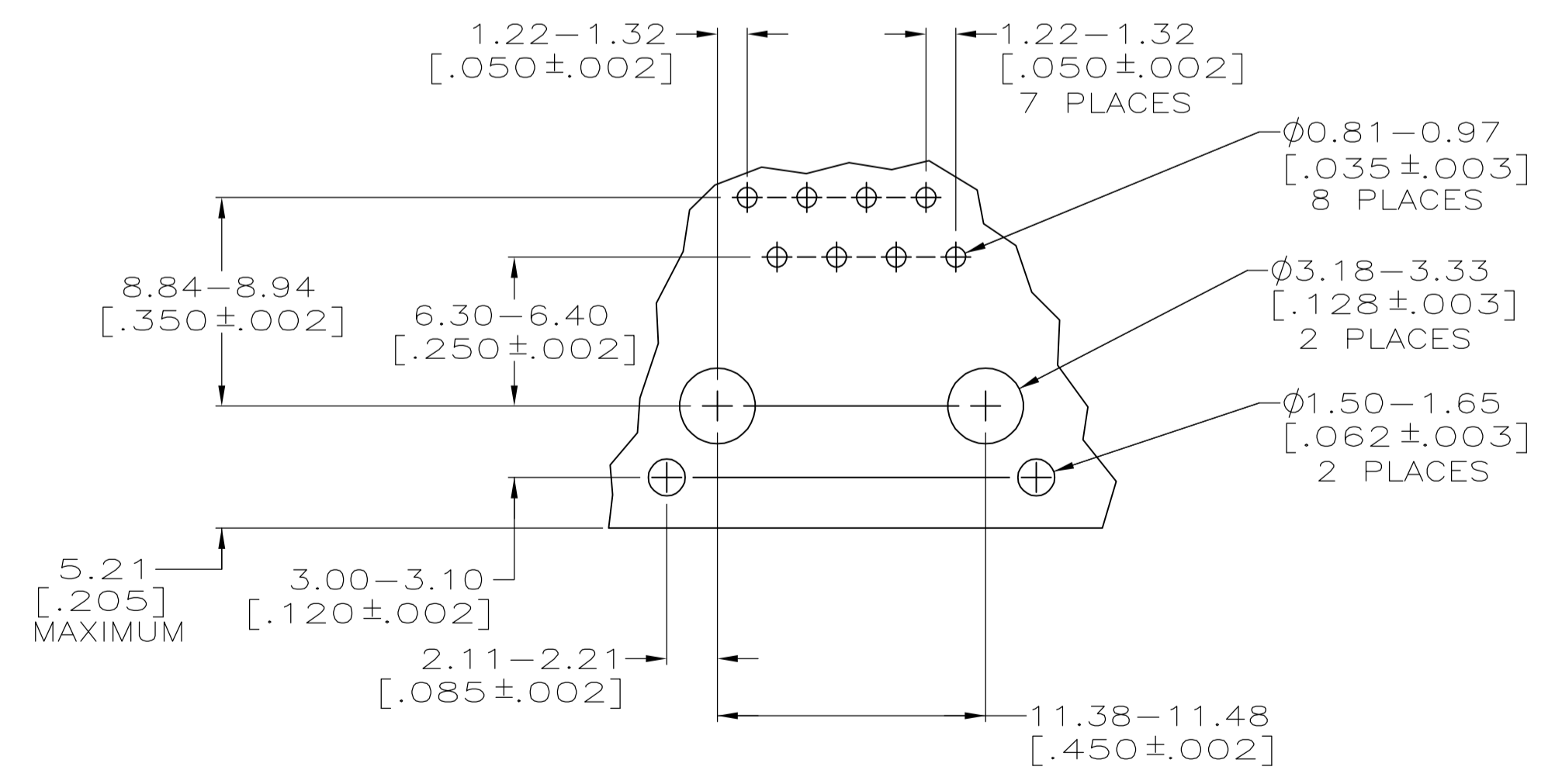


LOC	DIST	REVISIONS			
P	LTR	DESCRIPTION	DATE	BY	APPV
L		ECO-06-010069	31JULY06	LAM	JW



DETAIL B
SCALE 2:1



SUGGESTED PRINTED CIRCUIT BOARD
MOUNTING HOLE LAYOUT
(VIEW SHOWN IS CIRCUIT SIDE OF BOARD)

- 1 MATERIAL:
HOUSING - PBT POLYESTER BLACK.
TERMINAL - 0.36[.014] THICK PHOS-BRONZE PLATED WITH 1.27μm[.000050] THICK HARD GOLD IN LOCALIZED GOLD PLATE AREA AND 2.03μm[.000080] THICK TIN-LEAD IN SOLDER AREA OVER 1.27μm[.000050] THICK NICKEL UNDERPLATE.
SHIELD - 0.25[.010] THICK COPPER ALLOY, TIN-LEAD PLATED.
- 2 CAVITY CONFORMS TO FCC RULES AND REGULATIONS, PART 68, SUBPART F.
- 3 DIMENSIONS ARE MAXIMUM UNLESS OTHERWISE SPECIFIED.
- 4 BULK PACKAGED IN A TRAY.
- 5 32 ASSEMBLIES PACKAGED PER TUBE, SEE DETAIL B.

	DIM A	PACKAGED	PART NUMBER
OBSOLETE	1.78-2.79[.09±.02]	△	555153-6
	2.54-3.05[.11±.01]	△	555153-5
OBSOLETE	4.06-4.57[.17±.01]	△	555153-4
	3.30-4.32[.15±.02]	△	555153-3
	3.30-4.32[.15±.02]	△	555153-1

THIS DRAWING IS A CONTROLLED DOCUMENT.

DIMENSIONS: mm	TOLERANCES UNLESS OTHERWISE SPECIFIED:	DRAWING NO	SCALE
0 PLC ± -	1 PLC ± -	A1 00779	4:1
2 PLC ± -	3 PLC ± -	REV	1 OF 1
4 PLC ± -	ANGLES ± -	DATE	REV

MATERIAL: 1 FINISH: 1

THIS DRAWING IS A CONTROLLED DOCUMENT. DIN J. GALUCCI/UTA 20MAY94. GIK D. HUSSEY 24MAY94. APVD J. TONEY 25MAY94. Tyco Electronics Corporation Harrisburg, PA 17105-3608. MODULAR JACK ASSEMBLY, 8 POSITION, SHIELDED, LOW PROFILE, RIGHT ANGLE WITH PRINTED CIRCUIT BOARD GROUND AND PANEL STOPS. SIZE: A1 00779 C=555153. CUSTOMER DRAWING. SCALE: 4:1. SHEET: 1 OF 1. REV: L.